

TETRACOM: Technology Transfer in Computing Systems

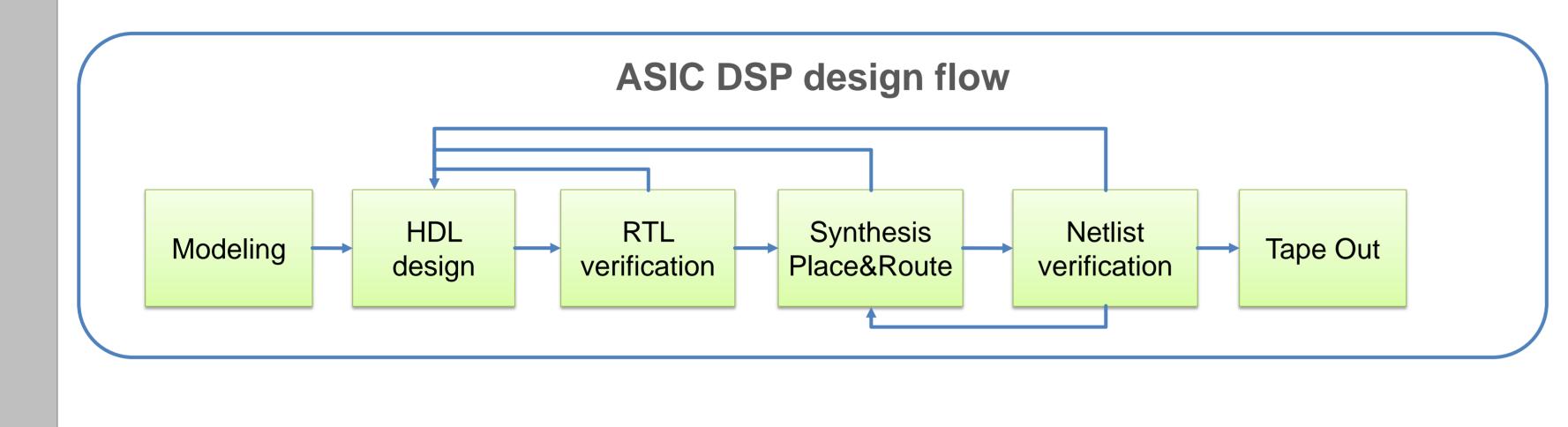


FP7 Coordination and Support Action to fund 50 technology transfer projects (TTP) in computing systems. This project has received funding from the European Union's Seventh Framework Programme for research, technological development and demonstration under grant agreement n^o 609491.

Design of a digital processor for 3D Hall sensors conditioning in automotive applications

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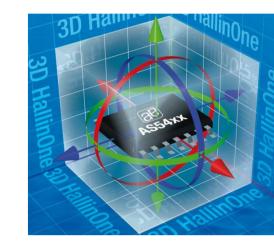
TTP Problem



- Great effort in "hardware" verification
- Many HDL design steps during design flow
- Hard redesign for bug fixing or specification changes
- Long time to market

3D Hall sensors

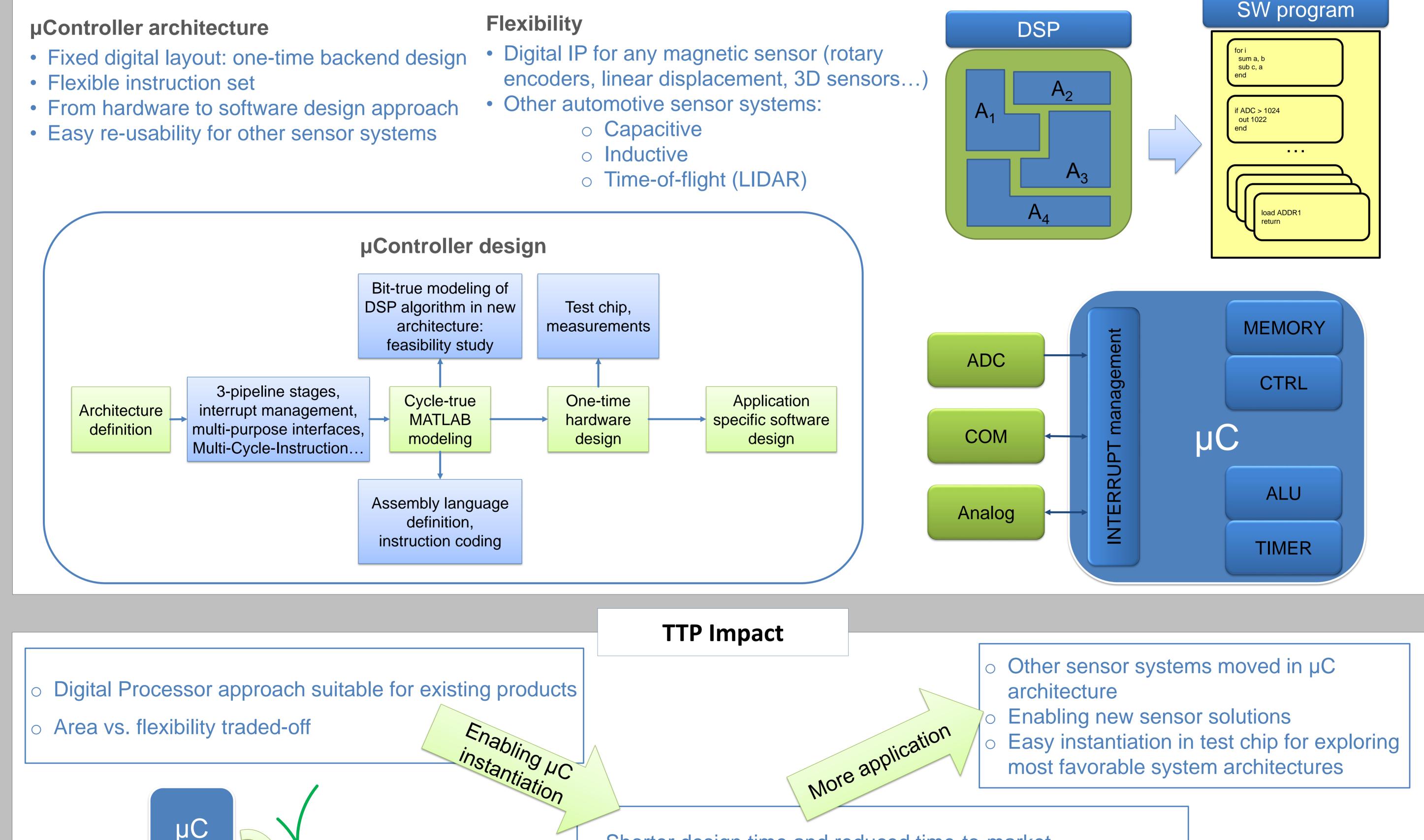
- Most complex processing algorithm in magnetic sensors applications
- AMS IP development in progress
- Flexible digital platform for test chips

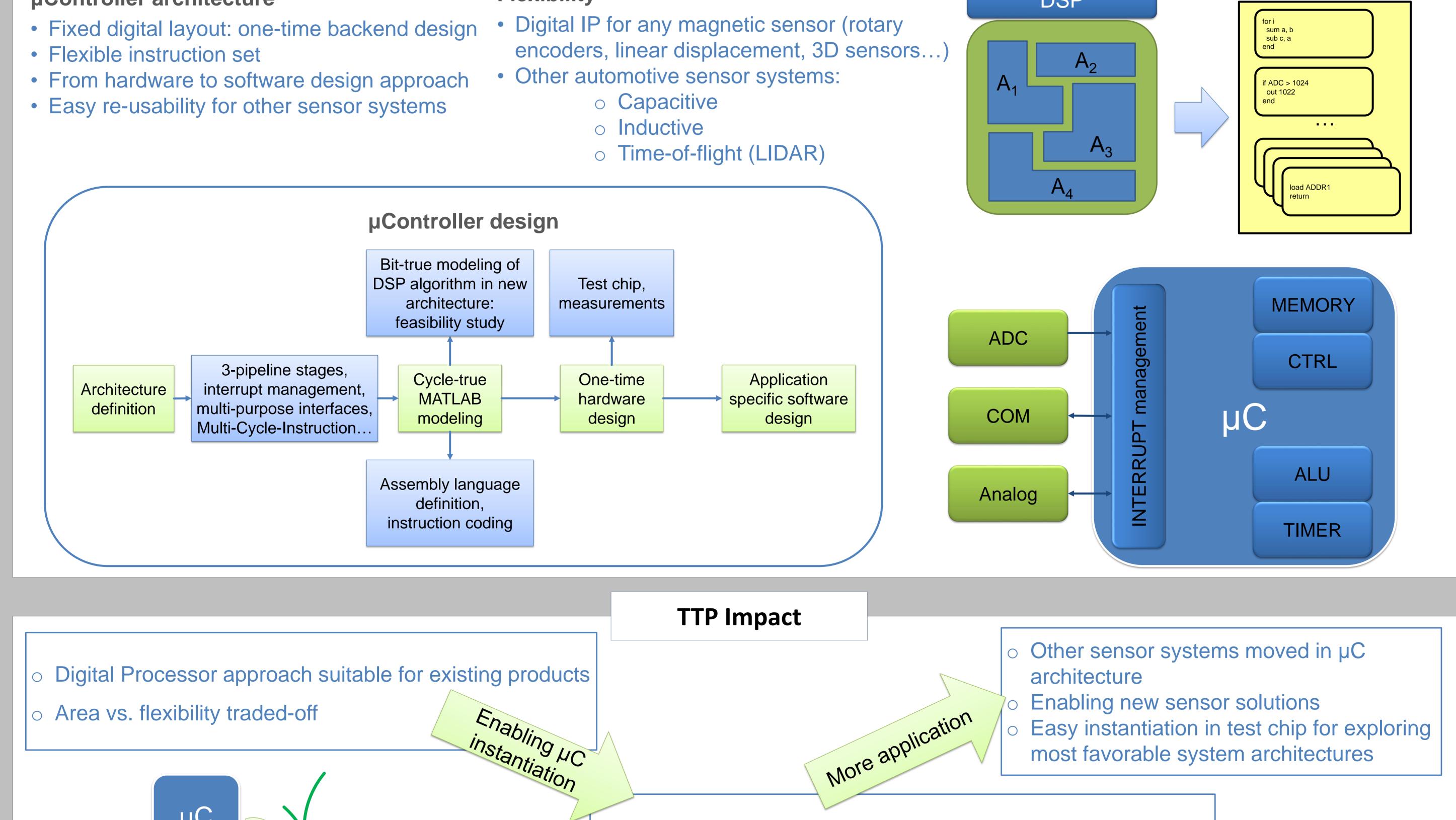


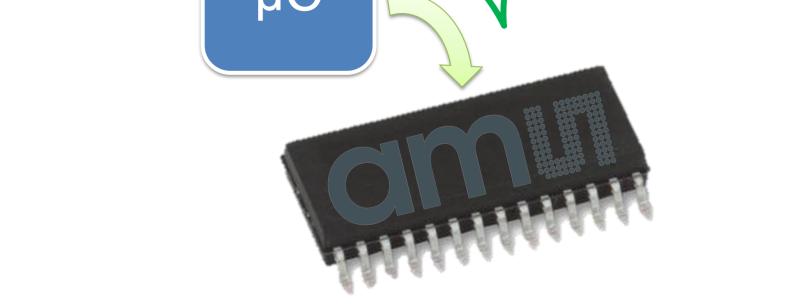
• Digital IP for any magnetic sensor (rotary

TTP Solution

- - Inductive







- Shorter design time and reduced time-to-market
- Easier Software verification \bigcirc
- Evaluation and test phase issues can be solved by a fast
 - micro controller program fixing
- Easy software redesign for bug fixing or specification changes

